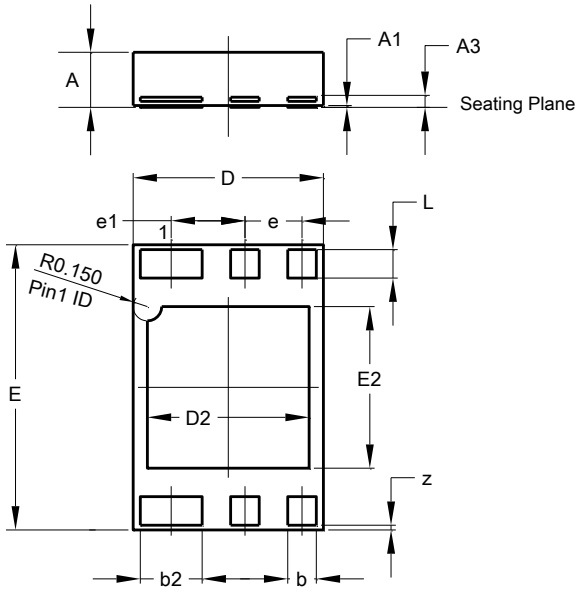
Package Outline Dimensions

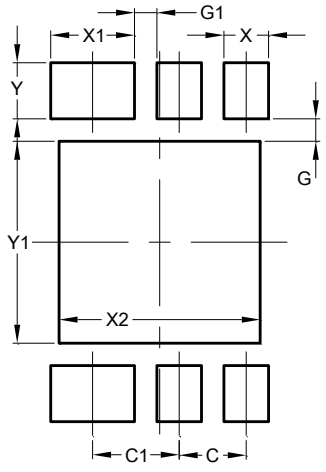
U-DFN2030-6 (Type C)



U-DFN2030-6 (Type C)			
Dim	**Min**	**Max**	**Typ**
A	0.50	0.60	--
A1	0.00	0.05	0.02
A3	--	--	0.127
b	0.25	0.35	0.30
b2	0.60	0.70	0.65
D	1.90	2.10	2.00
D2	1.60	1.80	1.70
E	2.90	3.10	3.00
E2	1.60	1.80	1.70
e	--	--	0.60
e1	--	--	0.775
L	0.25	0.35	0.30
z	0.0500 Ref		
All Dimensions in mm			

Suggested Pad Layout

U-DFN2030-6 (Type C)



Dimensions	Value (in mm)
C	0.600
C1	0.775
G	0.200
G1	0.200
X	0.400
X1	0.750
X2	1.800
Y	0.500
Y1	1.800

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.

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